

PCB Manufacturing Notes

General Info

Board dimensions – 40mm x 70mm
Number of layers – 2
Smallest hole – 0.3mm
Number of holes – Approx 120
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
Layer 01 (Top)	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

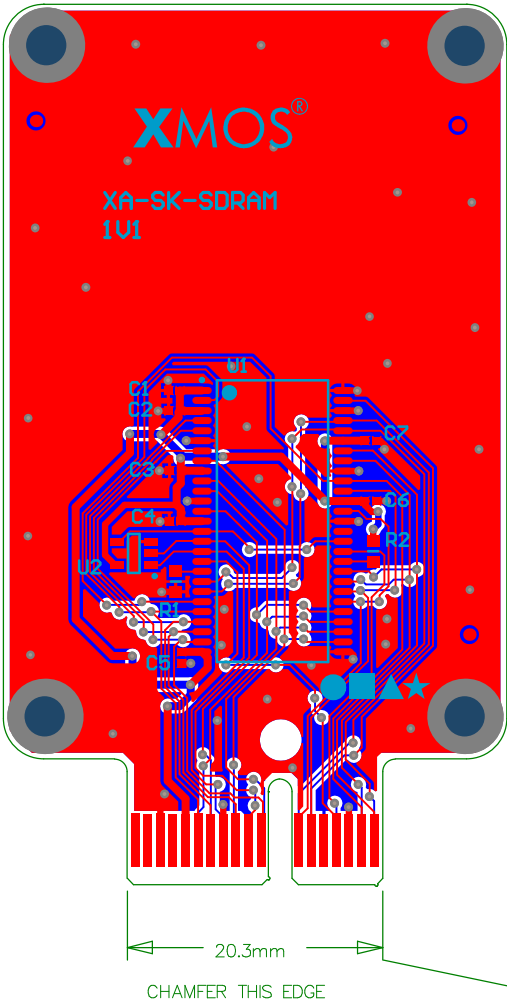
The supplier may not add copper thieving/balancing.

Finish

- A.) Conductive finish
Plating to be immersion gold.
- B.) Soldermask
Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.
- C.) Silkscreen
Colour white. Supplier should remove any silkscreen which overhangs pads.

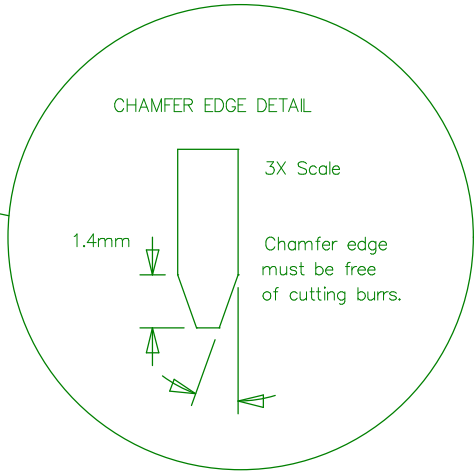
Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.
Hole size is finished size.



XMOS LTD = XIPCB-001 = 1V1 = 7 DECEMBER 2012

LAYER – FABRICATION INSTRUCTIONS
PCB COPPER LAYER 1 (TOP) SILKSCREEN TOP
PCB COPPER LAYER 2 (BOTTOM)



Project Name
XIPCB-001 (XA-SK-SDRAM)

Sheet	Date	Revision
A4	7 DECEMBER 2012	1V1

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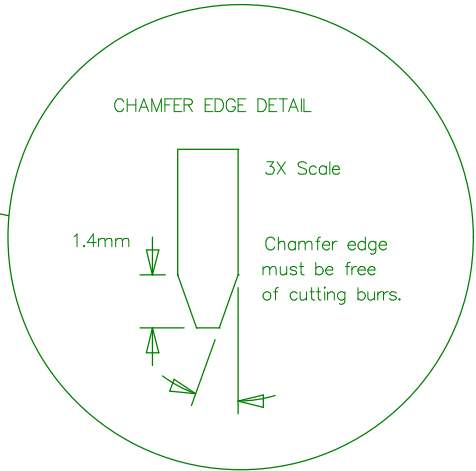
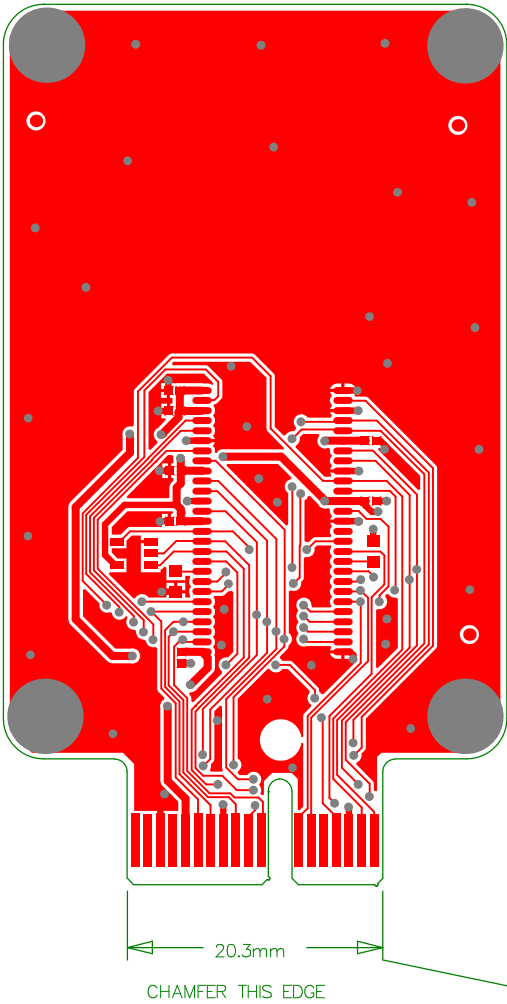
C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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FABRICATION INSTRUCTIONS
PCB COPPER LAYER 1 (TOP)



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Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
Layer 02 (Bottom)	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

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C.) Silkscreen

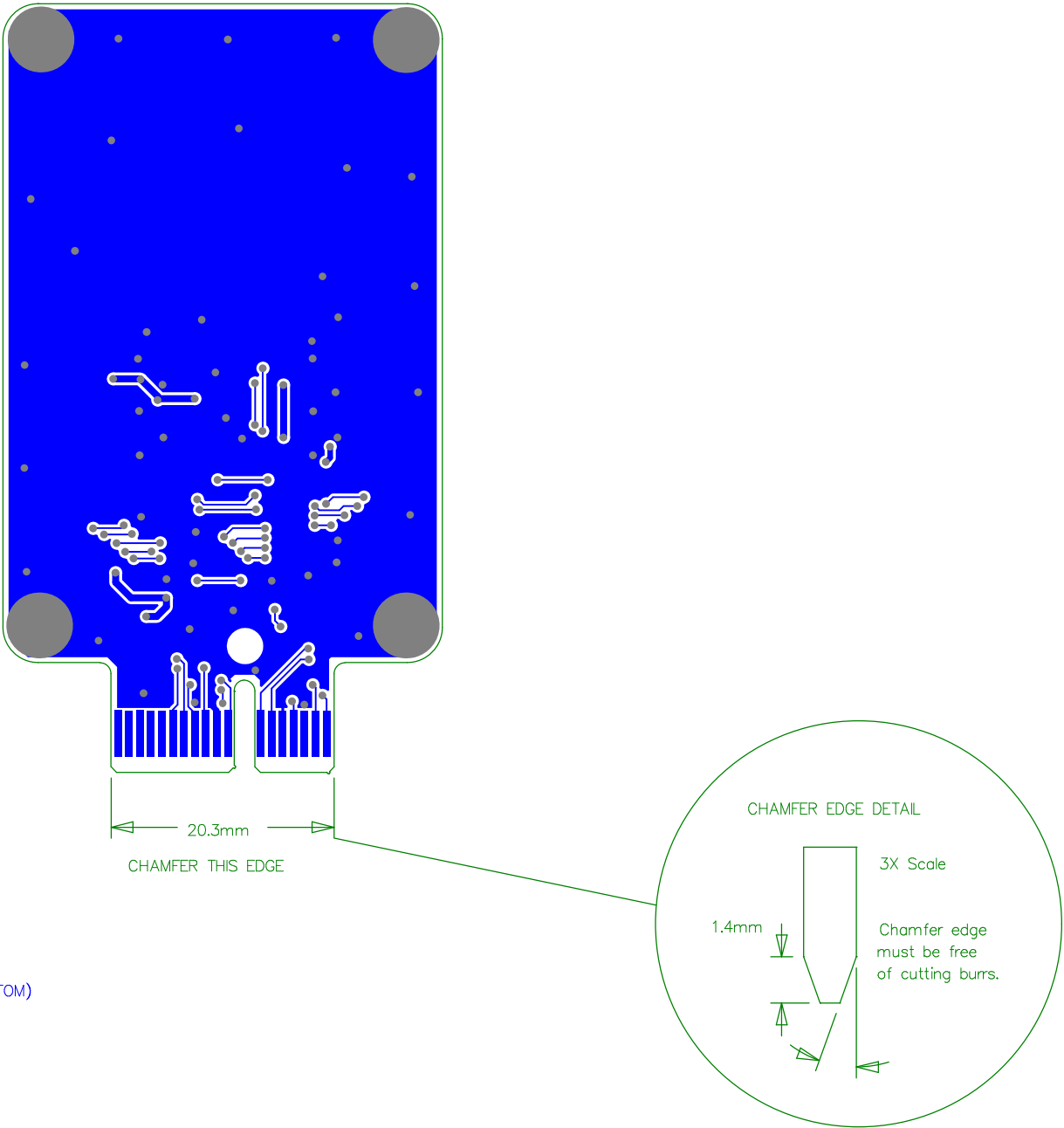
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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FABRICATION INSTRUCTIONS

PCB COPPER LAYER 2 (BOTTOM)



Project Name
XIPCB-001 (XA-SK-SDRAM)

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A4	7 DECEMBER 2012	1V1

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PCB Manufacturing Notes

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Smallest hole – 0.3mm
Number of holes – Approx 120
Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

Liquid photo imageable soldermask (green). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

C.) Silkscreen

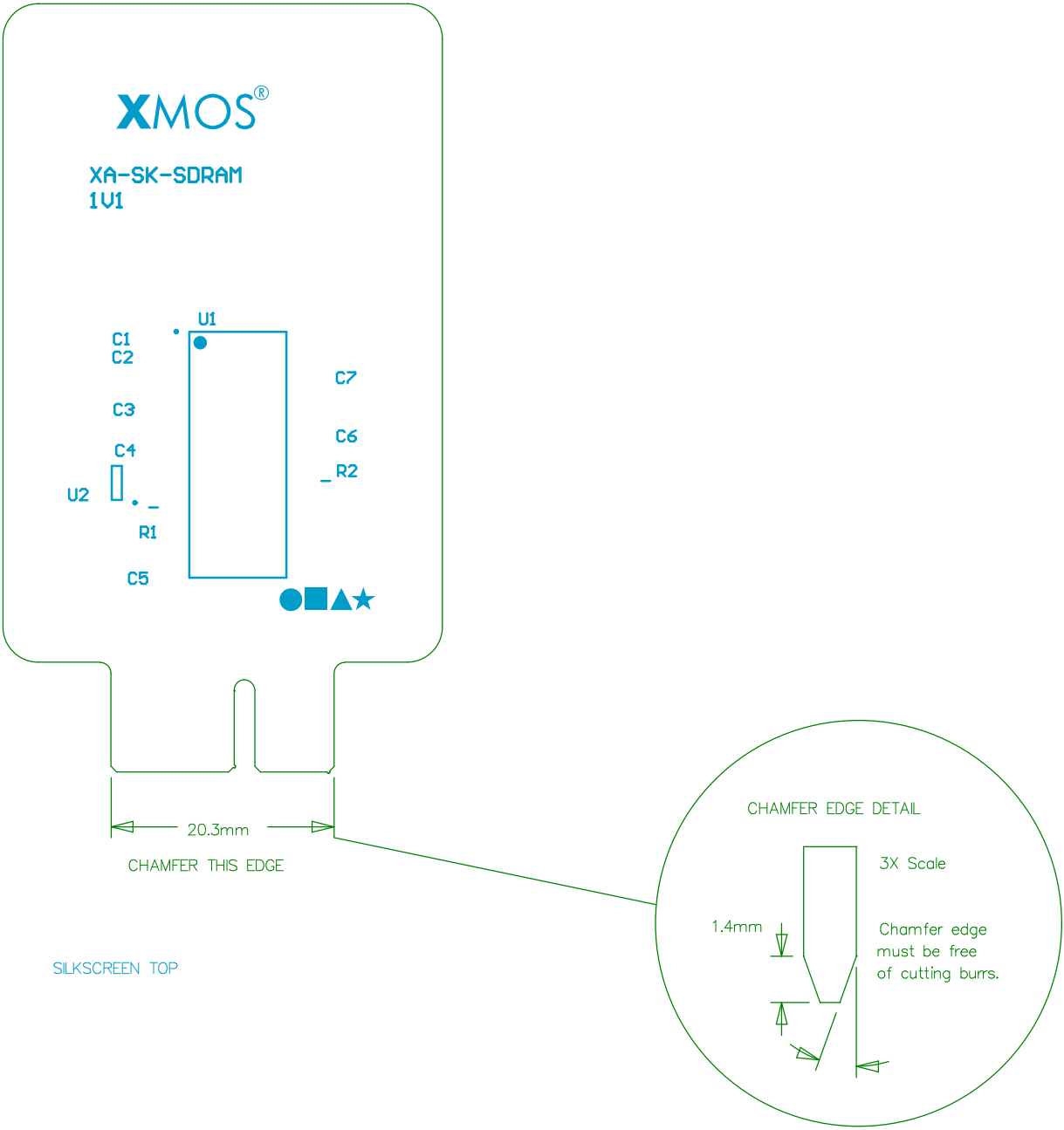
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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FABRICATION INSTRUCTIONS

SILKSCREEN TOP



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Minimum Track & Gap – 0.15mm
RoHS/Lead Free – Yes
Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

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C.) Silkscreen

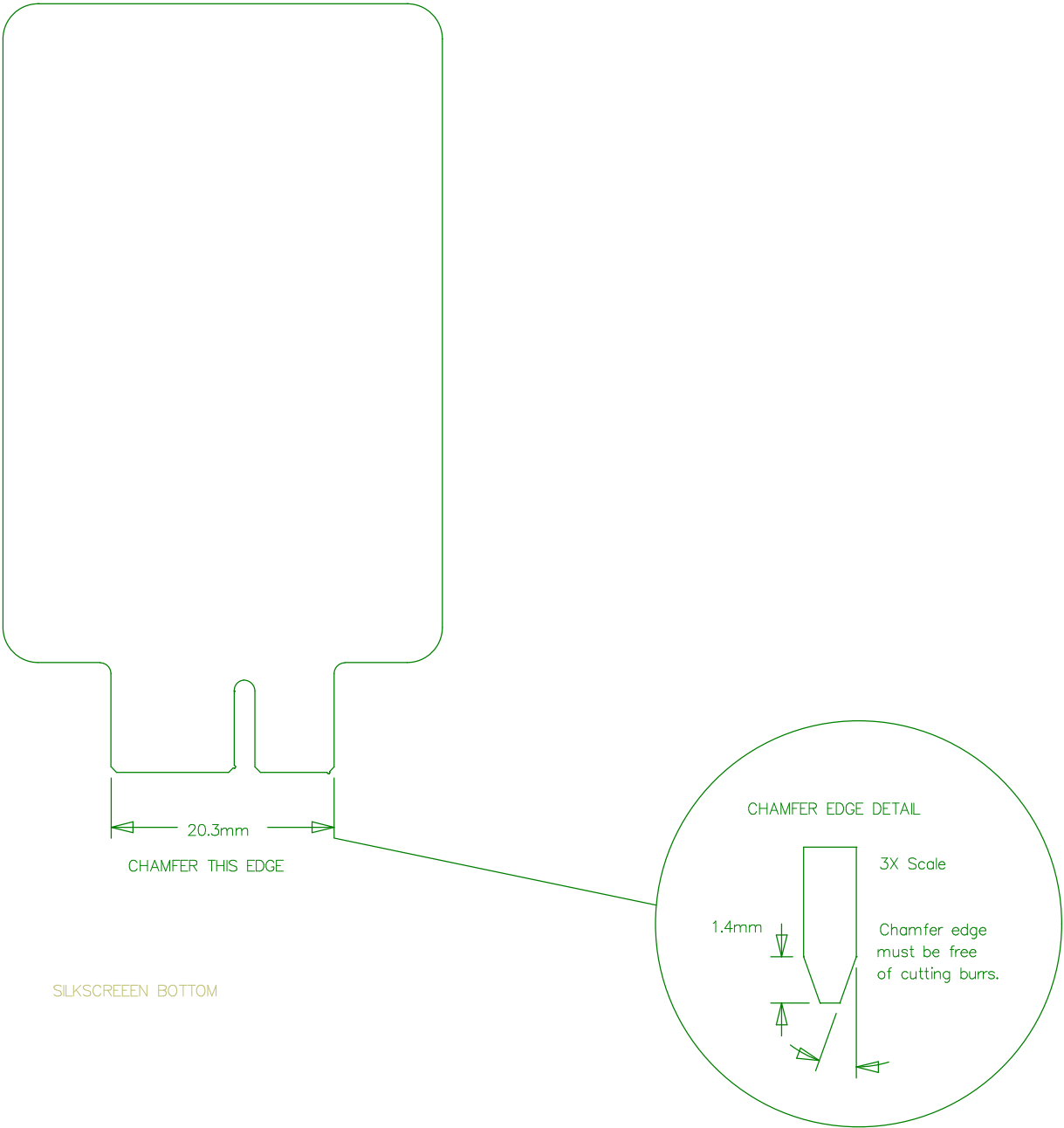
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

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FABRICATION INSTRUCTIONS

SLKSCREEN BOTTOM



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Minimum Track & Gap – 0.15mm
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Material – FR4 or equivalent

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

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Plating to be immersion gold.

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C.) Silkscreen

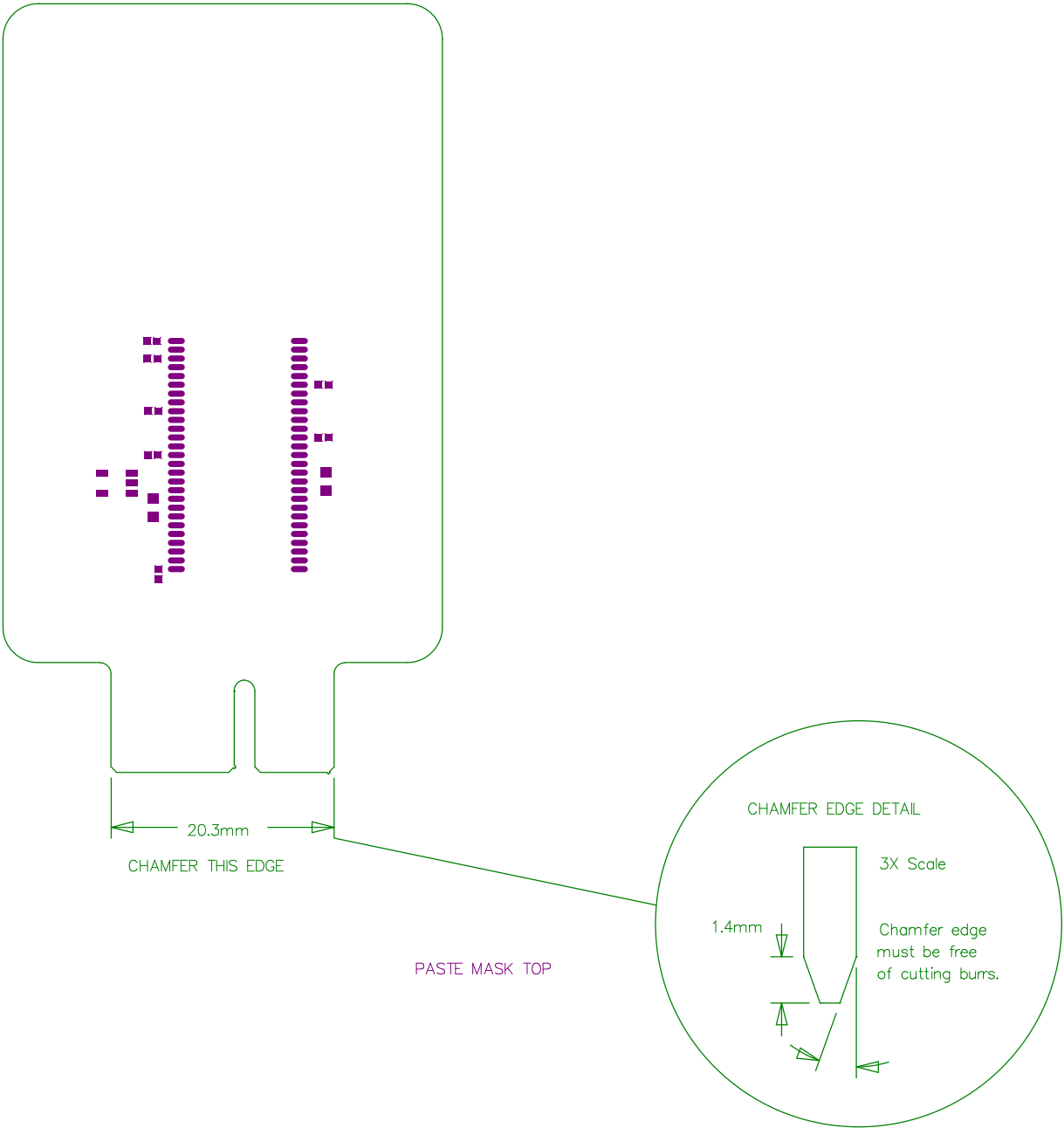
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FABRICATION INSTRUCTIONS

PASTE MASK TOP



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Layer	Copper Weight (Pre-Plating)
	0.5oz
	0.5oz

Finished board thickness to be 1.6mm ±0.1mm

Impedance Control

Not required.

Copper Thieving/Balancing

The supplier may not add copper thieving/balancing.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

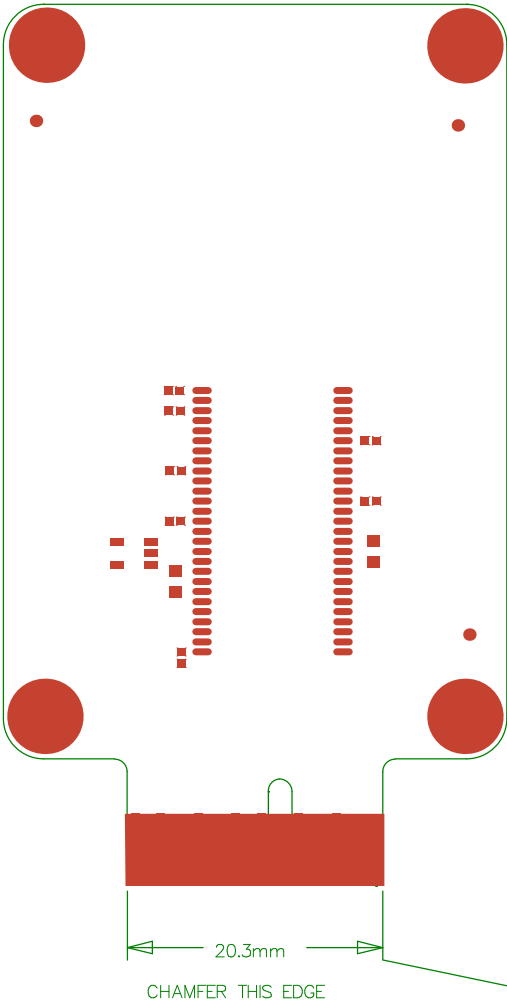
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FABRICATION INSTRUCTIONS

SOLDER MASK TOP



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XIPCB-001 (XA-SK-SDRAM)

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A4	7 DECEMBER 2012	1V1

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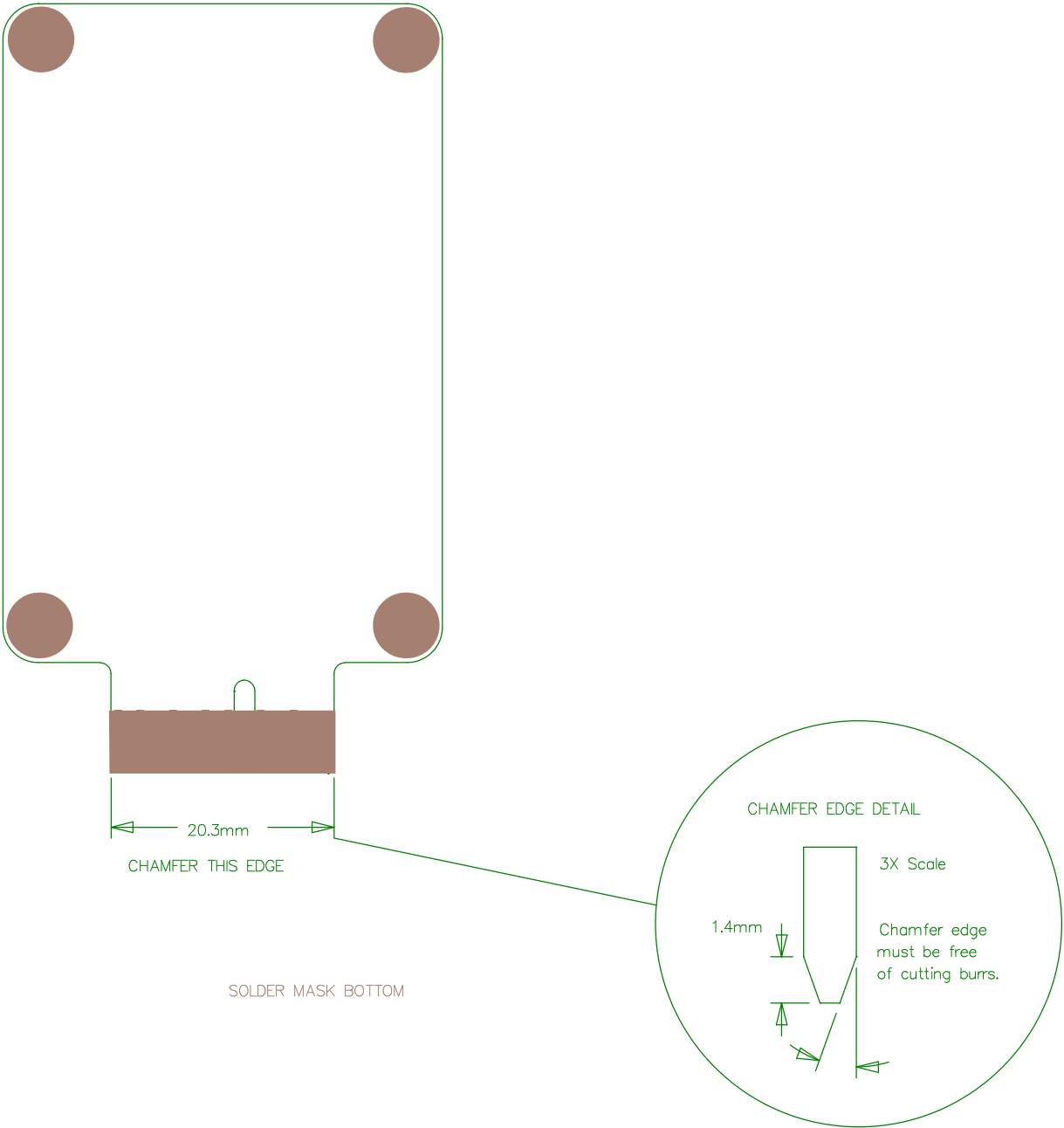
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FABRICATION INSTRUCTIONS

SOLDER MASK BOTTOM



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Project Name
XIPCB-001 (XA-SK-SDRAM)

Sheet	Date	Revision
A4	7 DECEMBER 2012	1V1

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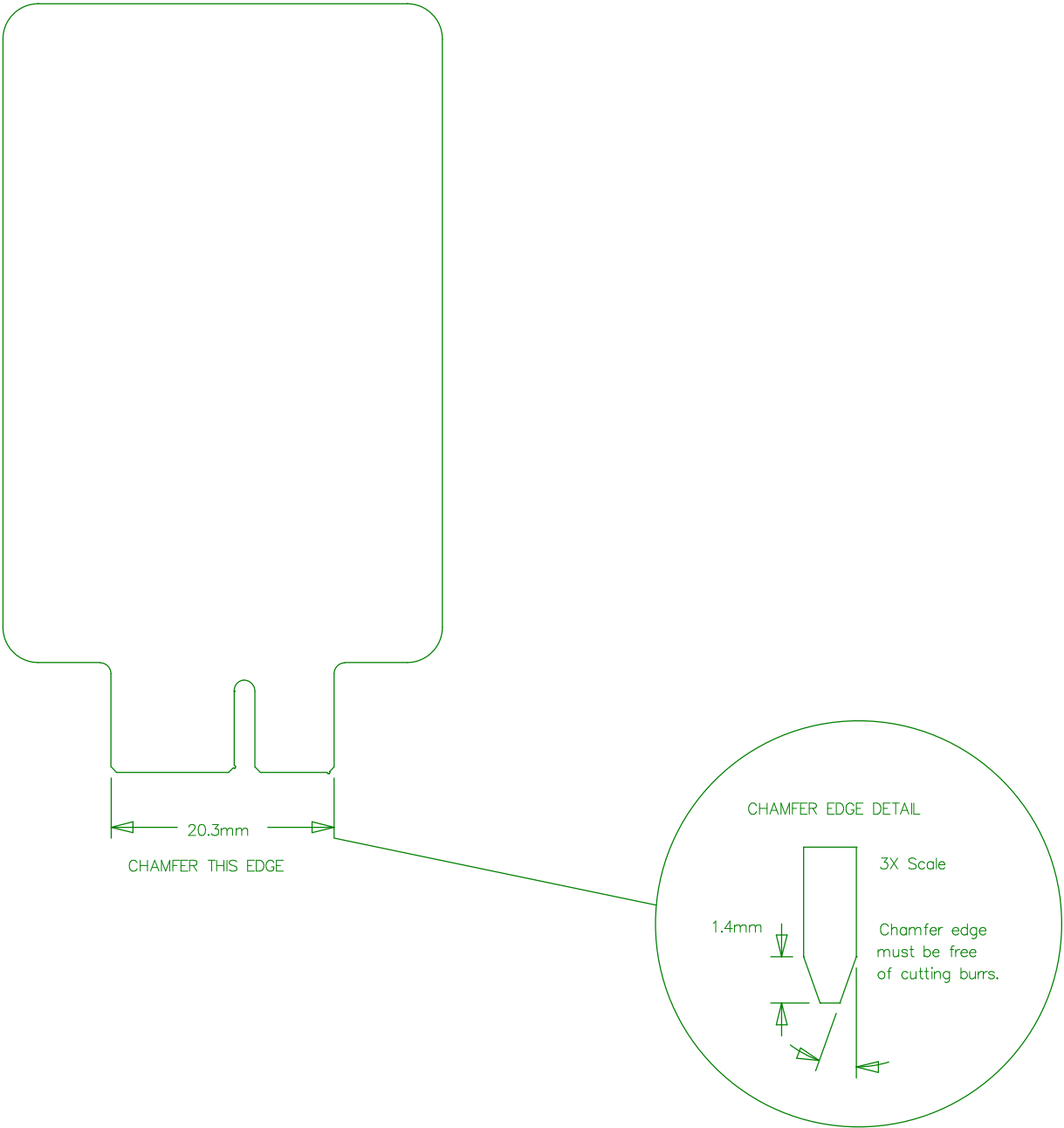
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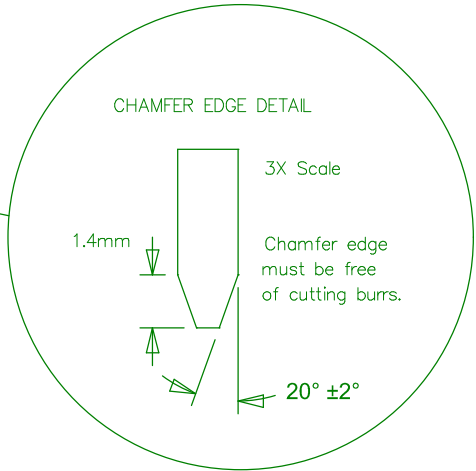
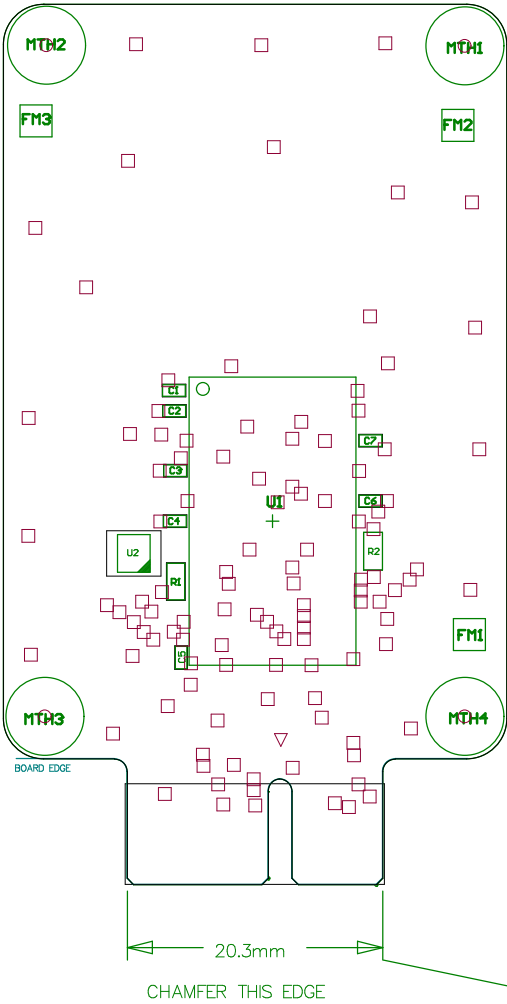
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FABRICATION INSTRUCTIONS

DRILL DRAWING

ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	112	0.3mm <11.811mil>	PTH	Round
▽	1	2.8mm <110.236mil>	NPTH	Round
○	4	3.2mm <125.984mil>	PTH	Round
	117 Total			

Drill Drawing.

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Project Name
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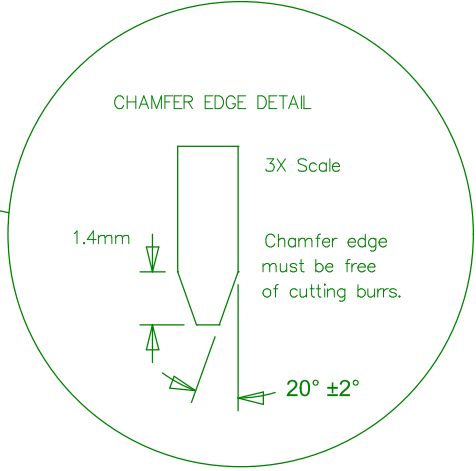
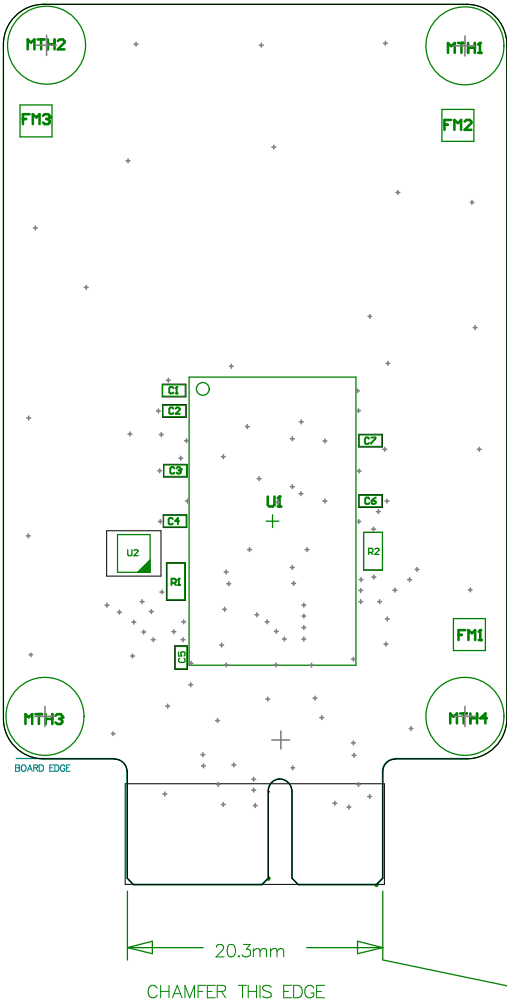
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ASSEMBLY DRAWING TOP
ASSEMBLY DRAWING BOTTOM



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Sheet	Date	Revision
A4	7 DECEMBER 2012	1V1

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BOM

SDRAM Slice

Source Data From:

Project:

Variant:

XIPCB-001-XA-SK-SDRAM.PrjPCB

XIPCB-001-XA-SK-SDRAM.PrjPCB

None



Report Date:

07/12/2012

16:00:38

Print Date:

07-Dec-12

4:00:42 PM

#	LibRef	Designator	Description	Quantity
1	E-01-0001	R1	RES 1k 0603 1%	1
2	E-01-0002	R2	RES 10k 0603 1%	1
3	E-02-0002	C1, C2, C3, C4, C5, C6, C7	MLCC 100nF 0402 X7R 16V	7
4	E-03-0022	U1	Memory, SDRAM, 64Mb (1Mx16x4), 54 Pin TSOP II	1
5	E-13-0117	U2	Single 2 Input Positive NOR, LVC series, SOT23-5	1
6	P-01-0011	PROD1, PROD2, PROD3, PROD4	Feet, Nylon, M3, 6mm Standoff	4
Approved			Notes	15